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21. A method of forming a thin film comprising the step of: forming an AgPdTi alloy thin film using a sputtering target material, the AgPdTi alloy comprising Pd in an amount ranging from 0.1 to 1.5 atomic %, Ti in an amount ranging from 0.1 to 2.9 atomic %, and Cu in an amount ranging from 0.1 to 3.5 atomic %.

22. The method of claim 21, wherein the thin film has a thickness from approximately 500 Angstroms to approximately 1500 Angstroms.

23. The method of claim 21, wherein the wavelength is less than or equal to 650 nm.

24. The method of claim 21, wherein the thin film has a thickness from approximately 500 Angstroms to approximately 1500 Angstroms; and wherein the wavelength is less than or equal to 650 nm.

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